



Form 1449 (Modified)

**Information Disclosure
Statement By Applicant**

(Use Several Sheets if Necessary)

Atty Docket No.
NSC1P194/P04836
Applicant:
MOSTAFAZADEH
Filing Date
10/26/00

Application No.:
09/698,736

Group
2811

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A						
	B						
	C						
	D						
	E						
	F						
	G						
	H						
	I						

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	J							
	K							
	L							
	M							
	N							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
LT	O	U.S. Patent Application No. 09/054,422, entitled "Lead Frame Chip Scale Package", filed April 2, 1998, inventor(s): Shahram Mostafazadeh
LT	P	U.S. Patent Application No. 09/528,540, entitled "Leadless Packaging Process Using a Conductive Substrate", filed March 20, 2000, inventor(s): Bayan et al.
LT	Q	U.S. Patent Application No. 09/590,551, entitled "Lead Frame Design for Chip Scale Package", filed June 2, 2000, inventor(s): Shahram Mostafazadeh
LT	R	U.S. Patent Application No. 09/698,784, entitled "Flip Chip Scale Package", filed October 26, 2000, inventor(s): Shahram Mostafazadeh
Examiner Luan Thai		Date Considered 3/2002

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.